



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Hou, *et al.* Docket No.: TSM03-0151
Serial No.: 10/691,019 Art Unit: TBD
Filed: October 22, 2003 Examiner: TBD
For: Method of Forming a Contact on a Silicon-on-Insulator Wafer

Certificate of Mailing via First Class Mail (37 C.F.R. § 1.8(a))

Date of Deposit: November 24, 2003

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Respectfully submitted,

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